

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method of fabricating a liquid crystal display device, comprising:
preparing first and second substrates having an active area and a dummy area;
forming at least one first column spacer on the active area on the second substrate;
forming at least one second column spacer in the dummy area on the second substrate;
forming a sealant in a periphery of the active area of the second substrate;
forming a liquid crystal layer between the first and second substrates; and
bonding the first and second substrates to each other.
2. (Original) The method of claim 1, wherein the sealant includes a photo-hardening sealant.
3. (Original) The method of claim 1, wherein the sealant includes a mixture of a thermo-hardening sealant and a photo-hardening sealant.
4. (Original) The method of claim 1, wherein the first and second column spacers are about 5 to 30 μm in width.
5. (Original) The method of claim 1, wherein the first and second column spacers are formed of organic resin.
6. (Original) The method of claim 1, further comprising forming at least one third column spacer outside the active area of the second substrate.

7. (Original) The method of claim 6, wherein the third column spacer is about 5 to 30 μm in width.

8. (Original) The method of claim 6, wherein the third column spacer is formed of organic resin.

9. (Canceled).

10. (Currently Amended) The method of claim [[1]], wherein the liquid crystal layer is applied on the first substrate.

11. (Original) The method of claim 1, further comprising forming a sliver pattern in a periphery of the active area of the first substrate.

12. (Original) The method of claim 1, wherein the bonding the first and second substrates to each other includes:

loading the second substrate on an upper stage of a bonding machine to face into the first substrate;

loading the first substrate on a lower stage of the bonding machine;

evacuating a chamber of the bonding machine;

aligning the first and second substrates; and

attaching the first and second substrates to each other.

13. (Original) The method of claim 12, further comprising venting the chamber to an atmospheric pressure to press the attached substrates by difference between an inner pressure of the bonded substrates and the atmospheric pressure.

14. (Original) The method of claim 12, further comprising applying a UV-ray to the attached substrates to harden the sealant.

15. (Original) The method of claim 1, wherein the first column spacer is formed on the wiring part of the first substrate.

16. (Original) The method of claim 1, further comprising:
forming a black matrix and a color filter layer on the second substrate; and
forming an overcoat layer on the color filter layer.
17. (Original) The method of claim 16, wherein the overcoat layer is patterned.
18. (Original) The method of claim 16, wherein the sealant has a line width smaller or greater than the black matrix.
19. (Original) The method of claim 1, further comprising forming a dummy color filter layer on the periphery of the active area of the second substrate.